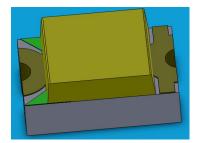
EVERLIGHT

DATASHEET

SMD • B 17-11ZSUBC/S3175/TR8



Features

- Package in 8mm tape on 7" diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow

solder process.

- Mono-color type.
- Pb-free.
- ESD Protection.
- The product itself will remain within RoHS compliant version.

Description

- The 17-11Z SMD LED is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature applications. etc.

Applications

- Backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in

telephone and fax.

- Flat backlight for LCD, switch and symbol.
- General use.

Device Selection Guide

Chip Materials	Emitted Color Resin C		Color	
InGaN	Blue		Water Clear	
Absolute Maximum Rat	tings (Ta=25)			
Parameter	Symbol	Rating	Unit	
Reverse Voltage	V _R	5	V	
Forward Current	I _F	10	mA	
eak Forward Current (Duty 1/10 @1KHz)	I _{FP}	100	mA	
Power Dissipation	Pd	40	mW	
Operating Temperature	T _{opr}	-40 ~ +85		
Storage Temperature	Tstg	-40 ~ +90		
Electrostatic Discharge	ESD _{HBM}	2000	V	
Soldering Temperature	T _{sol}	Reflow Soldering : 260 Hand Soldering : 350	for 10sec. for 3 sec.	

Electro-Optical Characteristics (Ta=25

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity	lv	2.8		7.2	mcd	_
Viewing Angle	201/2		140		deg	_
Peak Wavelength	р		468		nm	_
Dominant Wavelength	d	465		475	nm	I _F =1mA
Spectrum Radiation Bandwidth			25		nm	_
Forward Voltage	V _F	2.5		3.0	V	
Reverse Current	I _R			50	μA	V _R =5V
2. Tolerance of Fo	minous Intensity: ± ward Voltage: ±0.7 ward Voltage ±0.09	1nm				

Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
H1	2.8	3.6		
H2	3.6	4.5		L _ 1 - 2 - 2 A
J1	4.5	5.8	mcd	I _F =1mA
J2	5.8	7.2		

Note:

Tolerance of Luminous Intensity: ±11%

Bin Range of Dominant Wavelength

Group Bin	Min.	Max.	Unit	Condition
7	465.0	470.0		L _ 1 - 2
	470.0	475.0	nm	I _F =1mA

Bin Range Of Forward Voltage

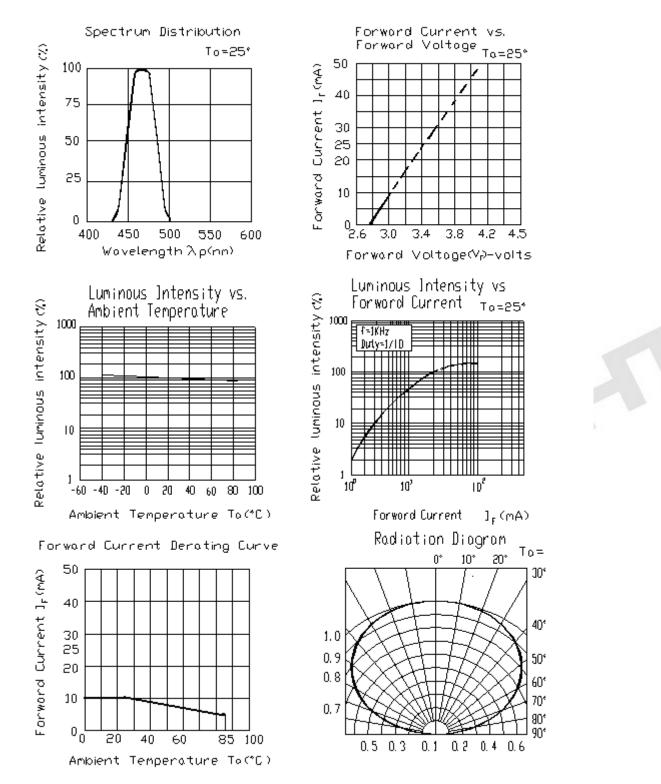
Note: Tolerance of Dor	ninant Wavelength: ±1nm			
Bin Range Of	Forward Voltage			
Bin Code	Min.	Max.	Unit	Condition
27-1	2.50	2.55		
27-2	2.55	2.60		
28-1	2.60	2.65		
28-2	2.65	2.70		
29-1	2.70	2.75		
29-2	2.75	2.80	V	I _F =1mA
30-1	2.80	2.85		
30-2	2.85	2.90		
31-1	2.90	2.95		
31-2	2.95	3.00		

Note:

1. Tolerance of Luminous Intensity: ±11%

2. Tolerance of Forward Voltage: ±0.05V

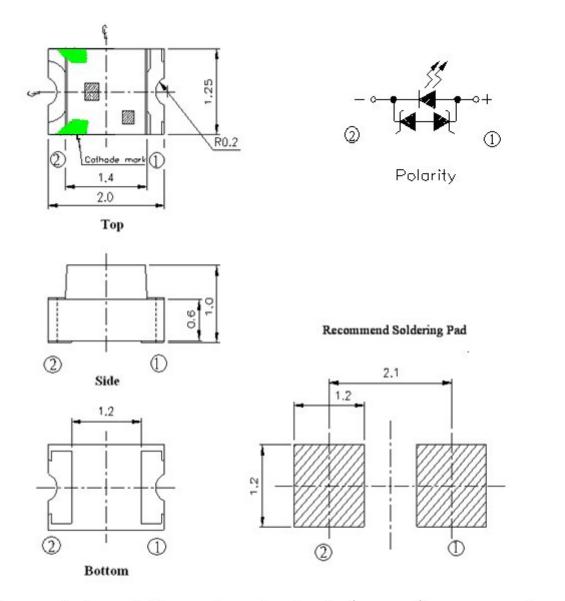
Typical Electro-Optical Characteristics Curves



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Package Dimension

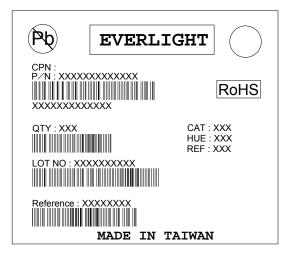


Suggested pad dimension is just for reference only. Please modify the pad dimension based on individual need.

Note: Tolerances unless mentioned ±0.1mm. Unit = mm

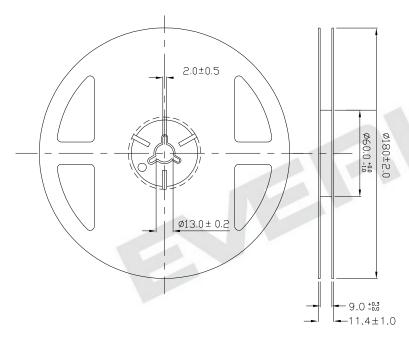


Label Explanation



- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Chromaticity Coordinates & Dom. Wavelength Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number

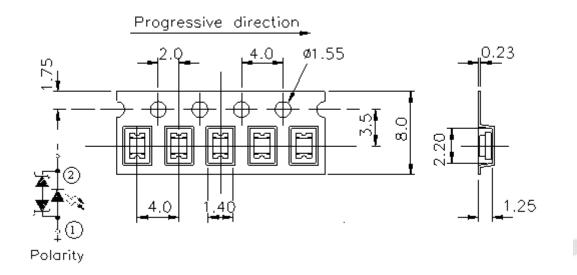
Reel Dimensions



Note: The tolerances unless mentioned is ±0.1mm ,Unit = mm



Carrier Tape Dimensions: Loaded quantity 3000 PCS per reel

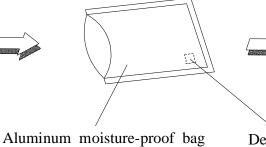


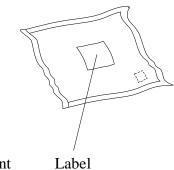
Note: The tolerances unless mentioned is ±0.1mm ,Unit = mm

Moisture Resistant Packaging









Label

Desiccant



Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big

current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package: The LEDs should be kept at 30 or less and 90%RH or less.

2.3 After opening the package: The LED's floor life is 1 year under 30 or less and 60% RH or less.

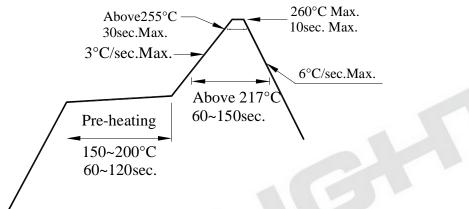
If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5 for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

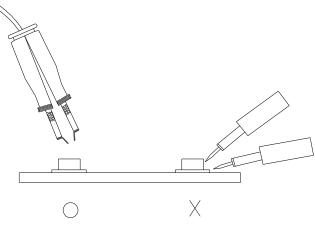
3.4 After soldering, do not warp the circuit board.

4.Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350 for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.





Application Restrictions

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.

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